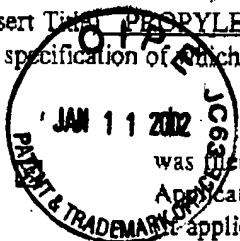


As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled  
(Insert Title) PROPYLENE-BASED RESIN COMPOSITION, EXCELLENT IN MOLDABILITY AND PROPERTIES  
the specification of which is attached hereto unless the following is checked



was filed on August 23, 2001 as United States Application Number 09/926,063 or PCT International Application Number PCT/JP00/09237 filed on December 26, 2000 and was amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) - (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed:

	<u>1999-368952</u>	<u>Japan</u>	<u>27/December/1999</u>	Priority Claimed
(List prior foreign applications. See note A on back of this page)	(Number)	(Country)	(Day/Month/Year Filed)	<u>XX</u> Yes ___ No
	_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	___ Yes ___ No

(See note B on back of this page) \_\_\_ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List Prior U.S. Applications)	<u>                    </u>	<u>                    </u>	<u>                    </u>
	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Abandoned)
	<u>                    </u>	<u>                    </u>	<u>                    </u>
	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Abandoned)
	<u>                    </u>	<u>                    </u>	<u>                    </u>
	(Appln. Serial No.)	(Filing Date)	(Status: Patented, Pending, Abandoned)



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Please direct all communications to the following address:



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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C  
above)

Full name of sole or first inventor (given name, family name) Masatoshi MATSUDAInventor's signature Masatoshi Matsuda Date 12/17/2001Residence Toyota-shi, Japan JPX Citizenship JapanesePost Office Address c/o Toyota Jidosha Kabushiki Kaisha1, Toyota-cho, Toyota-shi, Aichi-ken, 471-8572, JAPANFull name of second inventor (given name, family name) Hisayuki IWAIInventor's signature Hisayuki Iwai Date 13/17/2001Residence Toyota-shi, Japan JPX Citizenship JapanesePost Office Address c/o Toyota Jidosha Kabushiki Kaisha1, Toyota-cho, Toyota-shi, Aichi-ken, 471-8572, JAPANFull name of third inventor (given name, family name) Takayuki NAGAIInventor's signature Takayuki Nagai Date 12/17/2001Residence Toyota-shi, Japan JPX Citizenship JapanesePost Office Address c/o Toyota Jidosha Kabushiki Kaisha1, Toyota-cho, Toyota-shi, Aichi-ken, 471-8572, JAPANFull name of fourth inventor (given name, family name) Yukihito ZANKAInventor's signature Yukihito Zanka Date Dec. 13, 2001Residence Yokkaichi-shi, Japan JPX Citizenship JapanesePost Office Address c/o Japan Polychem Corporation, Products Research & Development Center1, Toho-cho, Yokkaichi-shi, Mie 510-0848, JAPAN

500 Inventor's signature Mitsuhiko Murayama Date Dec. 13, 2001  
Residence Yokkaichi-shi, Japan JPX Citizenship Japanese  
Post Office Address c/o Japan Polychem Corporation, Products Research & Development Center  
1, Toho-cho, Yokkaichi-shi, Mie 510-0848, JAPAN

600 Full name of sixth inventor (given name, family name) Yuji FUJITA  
Inventor's signature Yuji Fujita Date Dec. 13, 2001  
Residence Yokkaichi-shi, Japan JPX Citizenship Japanese  
Post Office Address c/o Japan Polychem Corporation, Products Research & Development Center  
1, Toho-cho, Yokkaichi-shi, Mie 510-0848, JAPAN

700 Full name of sixth inventor (given name, family name) Hironari SANO  
Inventor's signature Hironari Sano Date Dec 13 2001  
Residence Yokkaichi-shi, Japan JPX Citizenship Japanese  
Post Office Address c/o Mitsubishi Chemical Corporation, Yokkaichi Plant Chemical Science Laboratories  
1, Toho-cho, Yokkaichi-shi, Mie 510-8530, JAPAN

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